



US009414809B2

(12) **United States Patent**
Lee et al.

(10) **Patent No.:** **US 9,414,809 B2**
(45) **Date of Patent:** **Aug. 16, 2016**

(54) **PROBE FOR ULTRASONIC DIAGNOSTIC APPARATUS AND METHOD OF MANUFACTURING THE SAME**

(75) Inventors: **Sung Jae Lee**, Seoul (KR); **Jung Lim Park**, Seoul (KR); **Jae Yk Kim**, Seoul (KR)

(73) Assignee: **SAMSUNG MEDISON CO., LTD.**, Hongcheon-Gun, Gangwon-Do (KR)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 706 days.

(21) Appl. No.: **12/912,656**

(22) Filed: **Oct. 26, 2010**

(65) **Prior Publication Data**

US 2011/0105906 A1 May 5, 2011

(30) **Foreign Application Priority Data**

Oct. 29, 2009 (KR) 10-2009-0103771

(51) **Int. Cl.**

A61B 8/00 (2006.01)
B06B 1/06 (2006.01)
G10K 11/00 (2006.01)

(52) **U.S. Cl.**

CPC **A61B 8/4281** (2013.01); **B06B 1/0622** (2013.01); **G10K 11/004** (2013.01); **Y10T 29/49005** (2015.01)

(58) **Field of Classification Search**

CPC .. **A61B 8/4281**; **B06B 1/0622**; **G10K 11/004**; **Y10T 29/49005**

USPC **600/459**; **29/594**

See application file for complete search history.

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Primary Examiner — Jonathan Cwern

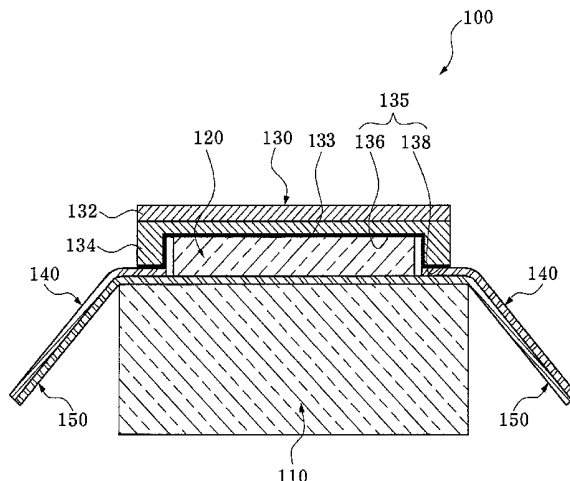
(74) Attorney, Agent, or Firm — McDermott Will & Emery LLP

(57)

ABSTRACT

A probe for an ultrasonic diagnostic apparatus and a method of manufacturing the same are disclosed. The probe includes a sound matching layer having a mounting groove, a piezo-electric member mounted on the mounting groove, a first connector interconnected to the sound matching layer, and a second connector interconnected to the piezoelectric member. The probe permits interconnection of the piezoelectric member to the first and second connectors to be performed rapidly and easily through a single bonding operation, thereby reducing manufacturing time while facilitating the manufacture of the probe.

7 Claims, 4 Drawing Sheets



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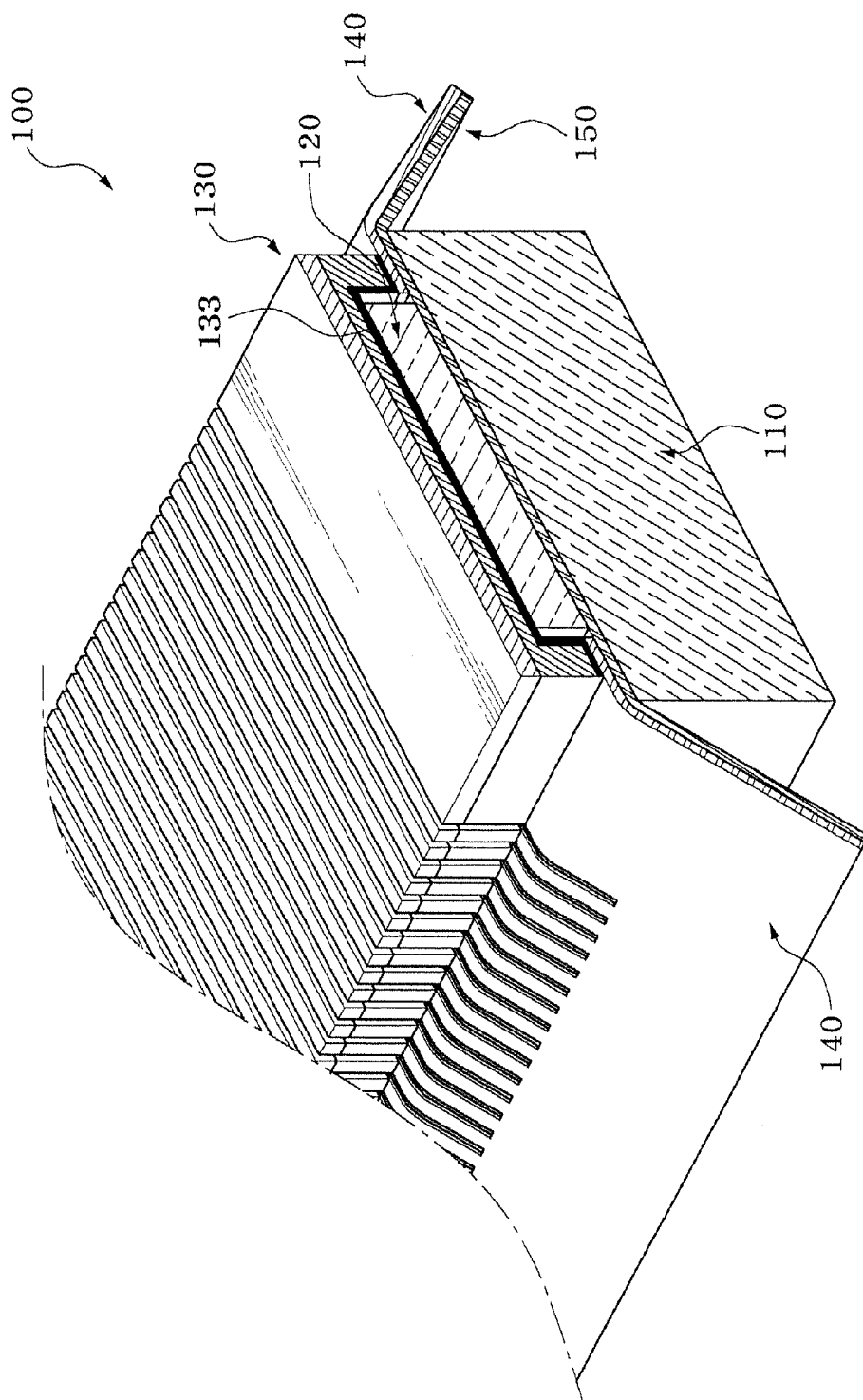


FIGURE 1

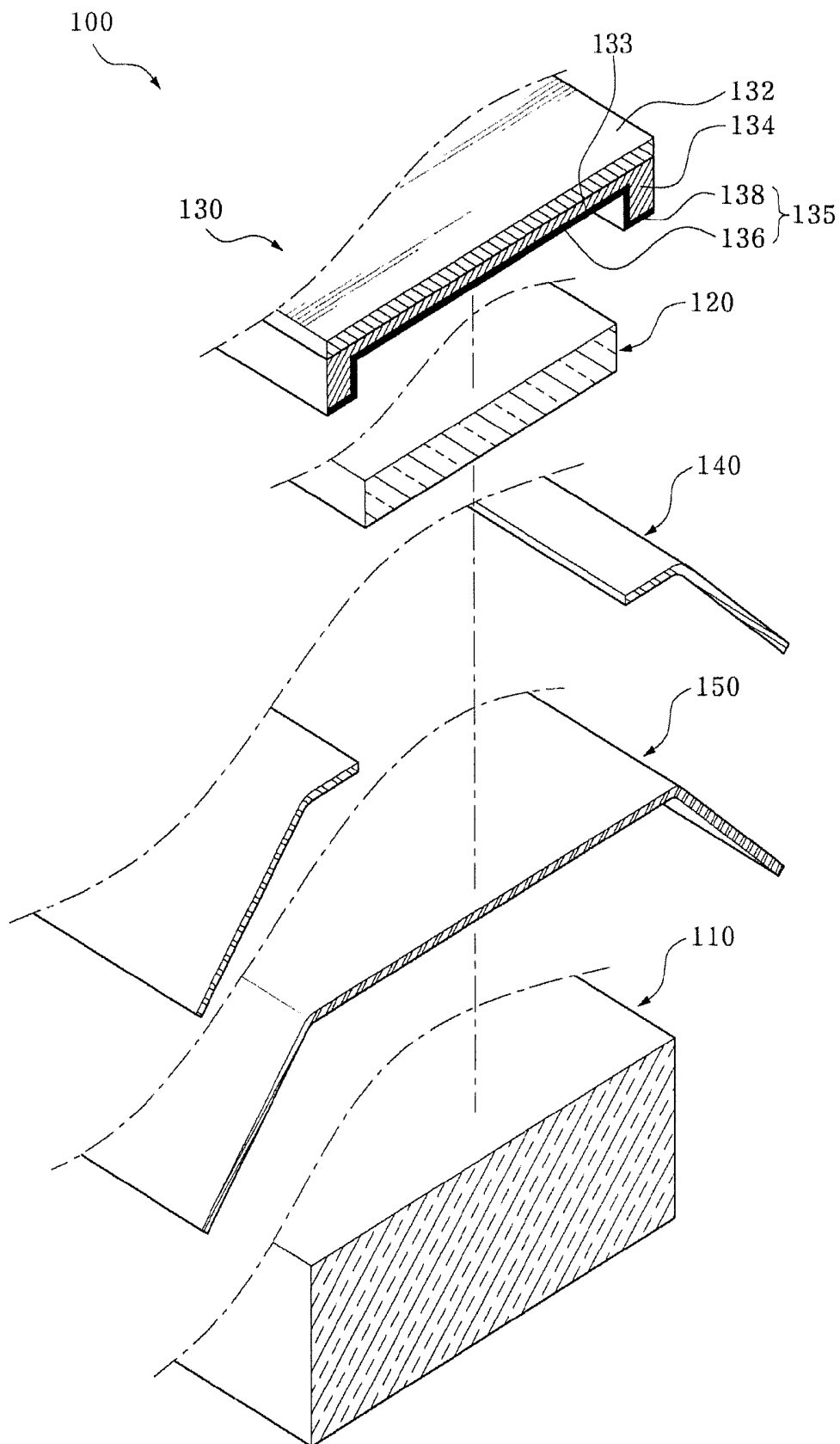


FIGURE 2

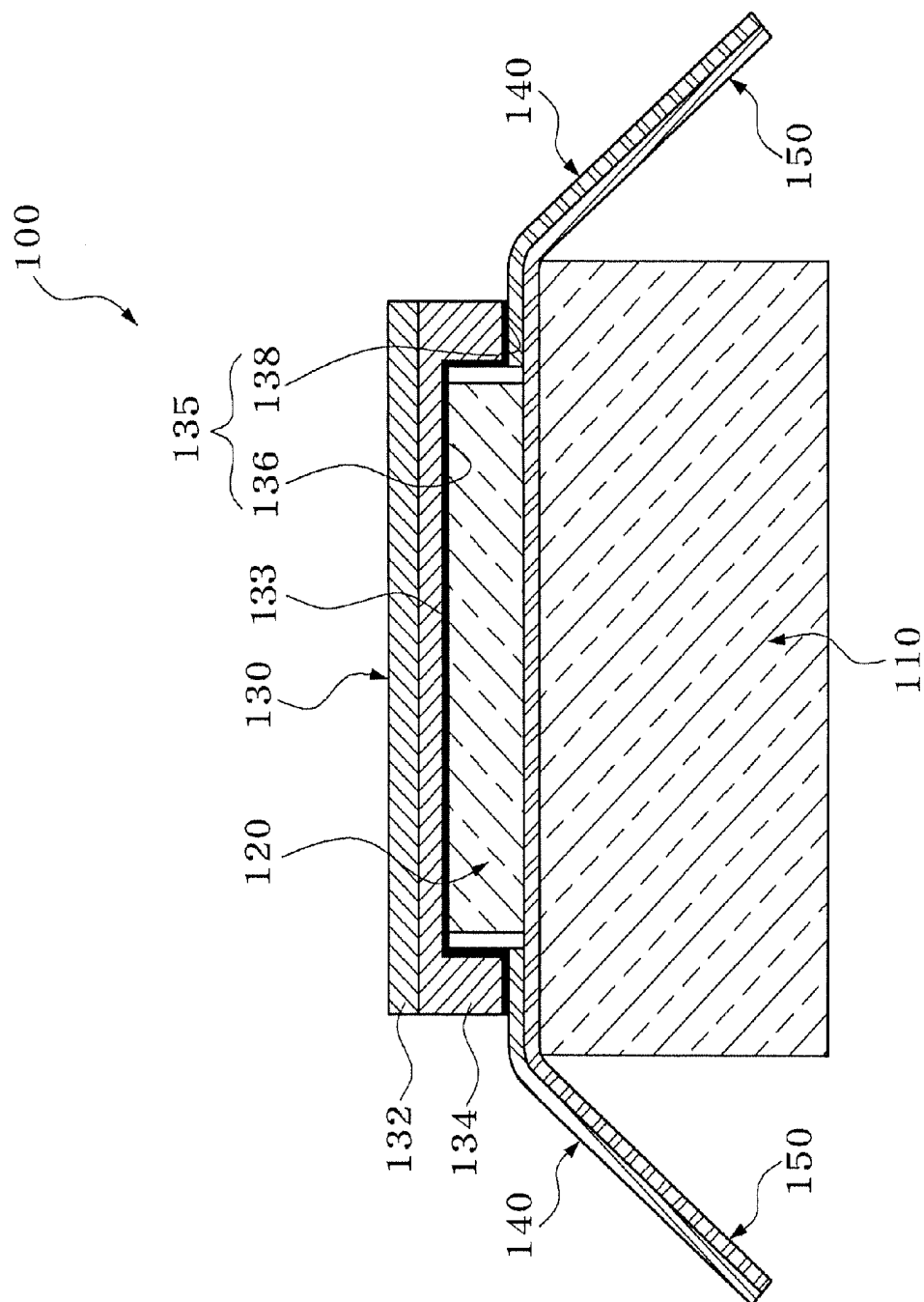
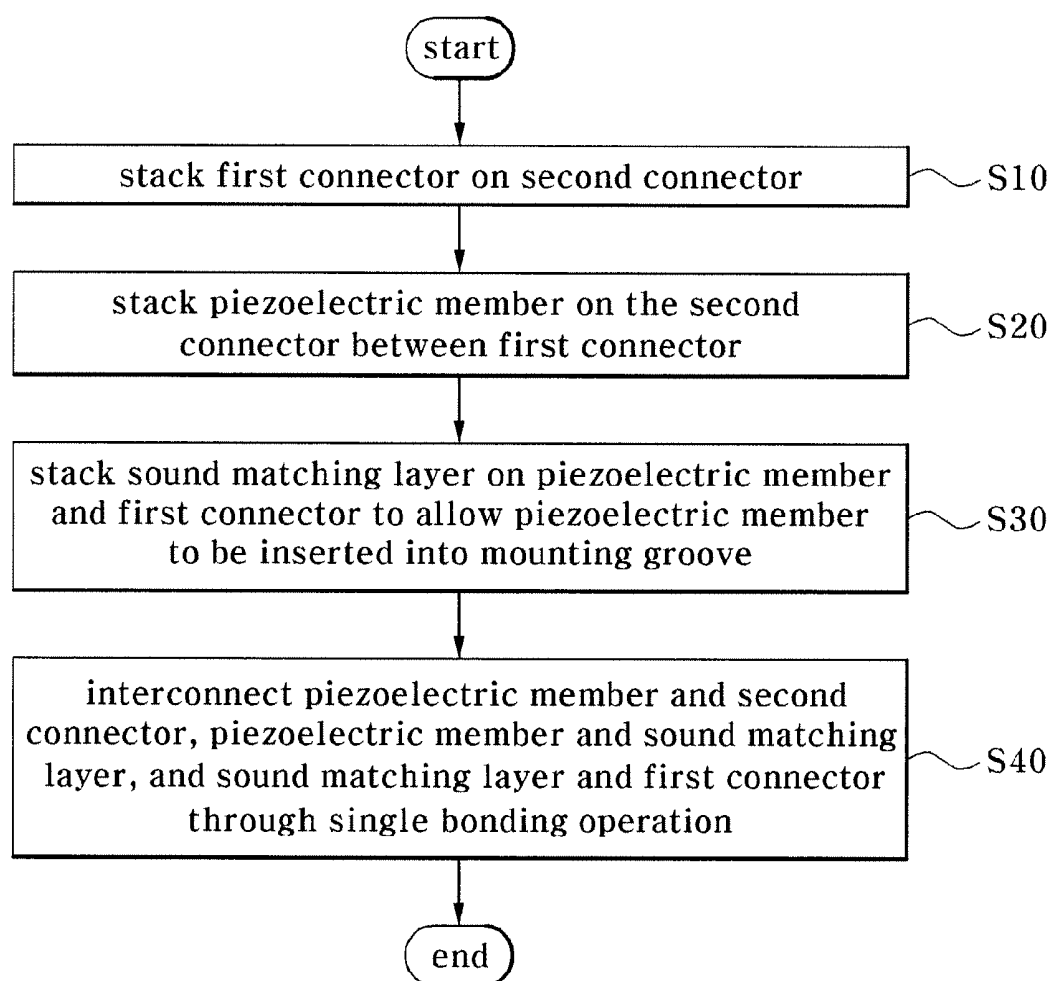


FIGURE 3

Fig. 4



PROBE FOR ULTRASONIC DIAGNOSTIC APPARATUS AND METHOD OF MANUFACTURING THE SAME

CROSS REFERENCE TO RELATED APPLICATIONS

This application claims the benefit of Korean Patent Application No. 10-2009-0103771, filed on Oct. 29, 2009, the entire contents of which are incorporated herein by reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to probes and, more particularly, to a probe for an ultrasonic diagnostic apparatus that generates internal images of a patient body using ultrasound waves, and a method of manufacturing the same.

2. Description of the Related Art

Generally, an ultrasonic diagnostic apparatus refers to a non-invasive apparatus that irradiates an ultrasound signal from a surface of a patient body towards a target internal organ beneath the body surface and obtains an image of a monolayer or blood flow in soft tissue from information in the reflected ultrasound signal (ultrasound echo-signal). The ultrasonic diagnostic apparatus has been widely used for diagnosis of the heart, the abdomen, the urinary organs, and in obstetrics and gynecology due to various merits such as small size, low price, real-time image display, and high stability through elimination of radiation exposure, as compared with other image diagnostic systems, such as X-ray diagnostic systems, computerized tomography scanners (CT scanners), magnetic resonance imagers (MRIs), nuclear medicine diagnostic apparatuses, and the like.

The ultrasonic diagnostic apparatus includes a probe which transmits an ultrasound signal to a patient body and receives the ultrasound echo-signal reflected therefrom to obtain the ultrasound image of the patient body.

The probe includes a transducer, a case with an open upper end, a cover coupled to the open upper end of the case to directly contact the body surface of the patient, and the like.

The transducer includes a piezoelectric layer in which a piezoelectric material converts electrical signals into sound signals or vice versa while vibrating, a sound matching layer reducing a difference in sound impedance between the piezoelectric layer and a patient body to allow as much of the ultrasound waves generated from the piezoelectric layer as possible to be transferred to the patient body, a lens layer focusing the ultrasound waves, which travel in front of the piezoelectric layer, onto a predetermined point, and a backing layer blocking the ultrasound waves from traveling in a rearward direction of the piezoelectric layer to prevent image distortion.

The piezoelectric layer includes a piezoelectric member and electrodes provided to upper and lower ends of the piezoelectric member, respectively. Further, a printed circuit board (PCB) is bonded to the piezoelectric layer. The PCB is provided with wiring electrodes that are connected to the electrodes of the piezoelectric layer to transfer signals from the piezoelectric member. The PCB is connected to the piezoelectric layer by connecting the wiring electrodes of the PCB to the electrodes of the piezoelectric layer.

In fabrication of the probe as above, connection between the wiring electrodes of the PCB and the electrodes of the piezoelectric layer is a laborious operation, which requires significant fabrication time and causes deterioration in per-

formance of the probe due to low durability and non-uniformity on the connection therebetween. Therefore, there is a need to solve such problems.

SUMMARY OF THE INVENTION

The present invention is conceived to solve the problems of the related art as described above, and an aspect of the present invention is to provide an improved probe for an ultrasonic diagnostic apparatus configured to allow easy manufacture of the probe while preventing deterioration in performance caused by defective connection between a piezoelectric layer and a PCB, and a method of manufacturing the same.

In accordance with one aspect of the invention, a probe for an ultrasonic diagnostic apparatus includes a sound matching layer having a mounting groove; a piezoelectric member having an upper face and a lower face, the piezoelectric member mounted within the mounting groove such that the upper face is coupled to the sound matching layer; a first connector coupled to the sound matching layer; and a second connector coupled to the first connector and to the lower face of the piezoelectric member.

The mounting groove may include a contact part formed parallel to the piezoelectric member and coupled to the upper face of the piezoelectric member; and an extension part extending from the contact part towards the first connector.

The first connector may be coupled to the extension part. The first connector may include a right first connector and a left first connector. The right first connector may be coupled to the extension part and the second connector. The left first connector may be coupled to the extension part and the second connector.

The mounting groove may have a bracket ("⌋") shape.

The first connector and the second connector may include a flexible printed circuit board (FPCB).

In accordance with another aspect of the invention, a method of manufacturing a probe for an ultrasonic diagnostic apparatus may include stacking a first connector on a second connector; stacking a piezoelectric member on the second connector between the first connector; stacking a sound matching layer having a mounting groove on the piezoelectric member and the first connector so that the piezoelectric member is disposed within the mounting groove; and coupling a lower face of the piezoelectric member and the second connector, an upper face of the piezoelectric member and the sound matching layer, and the sound matching layer and the first connector through a single bonding operation.

In the coupling through a single bonding operation, the first connector may be coupled only to the sound matching layer.

As such, the probe for an ultrasonic diagnostic apparatus and the method of manufacturing the same according to one embodiment can eliminate laborious operation such as soldering or welding, and permit interconnection of a piezoelectric member to first and second connectors to be performed rapidly and easily through a single bonding operation, thereby reducing manufacturing time while facilitating the manufacture of the probe.

Further, according to the embodiment, the interconnection of the piezoelectric member to the first and second connectors may be performed with the first and second connectors stably positioned, so that durability and uniformity of connected portions are enhanced, thereby preventing deterioration in performance of the probe due to failure of the connection between the piezoelectric member and the first and second connectors.

Further, according to the embodiment, since the first connector is connected to the piezoelectric member via the sound

matching layer instead of being directly connected thereto, the first connector is not disposed between the backing layer and the piezoelectric layer, so that performance of the piezoelectric member can be enhanced and the length of the first connector is decreased while reducing influence of impedance, thereby reducing manufacturing costs.

BRIEF DESCRIPTION OF THE DRAWINGS

The above and other aspects, features and advantages of the invention will become apparent from the following description of embodiments given in conjunction with the accompanying drawings, in which:

FIG. 1 is a perspective view of a probe for an ultrasonic diagnostic apparatus according to one embodiment of the present invention;

FIG. 2 is an exploded perspective view of the probe shown in FIG. 1;

FIG. 3 is a cross-sectional view of the probe shown in FIG. 1; and

FIG. 4 is a flowchart of a method of manufacturing a probe for an ultrasonic diagnostic apparatus according to one embodiment of the invention.

DETAILED DESCRIPTION OF THE EMBODIMENT

Exemplary embodiments of the invention will now be described in detail with reference to the accompanying drawings. It should be noted that the drawings are not to precise scale and may be exaggerated in thickness of lines or size of components for descriptive convenience and clarity only. Furthermore, terms used herein are defined by taking functions of the invention into account and can be changed according to the custom or intention of users or operators. Therefore, definition of the terms should be made according to overall disclosures set forth herein.

FIG. 1 is a perspective view of a probe for an ultrasonic diagnostic apparatus according to one embodiment of the invention, FIG. 2 is an exploded perspective view of the probe shown in FIG. 1, and FIG. 3 is a cross-sectional view of the probe shown in FIG. 1.

Referring to FIGS. 1 to 3, a probe 100 for an ultrasonic diagnostic apparatus according to this embodiment includes a backing layer 110, a piezoelectric member 120, a sound matching layer 130, a first connector 140, and a second connector 150.

The backing layer 110 is disposed behind the piezoelectric member 120. The backing layer 110 reduces a pulse width of an ultrasound wave by suppressing free vibration of the piezoelectric member 120 and prevents image distortion by blocking unnecessary propagation of the ultrasound wave in the rearward direction of the piezoelectric member 120. The backing layer 110 may be formed of a material containing a rubber to which epoxy, tungsten powder, and the like are added.

The piezoelectric member 120 is disposed in front of the backing layer 110. The piezoelectric member 120 generates ultrasound waves using a resonance phenomenon and may be formed of a ceramic of lead zirconate titanate (PZT), a PZNT single crystal made of a solid solution of lead zinc niobate and lead titanate, a PZMT single crystal made of a solid solution of lead magnesium niobate and lead titanate, or the like.

The piezoelectric member 120 is formed with electrodes (not shown). According to this embodiment, the electrodes are formed on opposite sides of the piezoelectric member 120, that is, on a front side and a rear side of the piezoelectric

member 120, respectively. The electrodes may be formed of a highly conductive metal such as gold, silver, or copper.

One of the electrodes formed on the opposite sides of the piezoelectric member 120 corresponds to a positive electrode (signal electrode) of the piezoelectric member 120 and the other corresponds to a negative electrode (ground electrode) of the piezoelectric member 120. The electrodes are formed such that the positive electrode is separated from the negative electrode. In this embodiment, the electrode formed on one side of the piezoelectric member 120 is illustrated as the negative electrode, and the electrode formed on the other side of the piezoelectric member 120 is illustrated as the positive electrode.

The sound matching layer 130 is disposed in front of the backing layer 110. The sound matching layer 130 allows ultrasound signals generated from the piezoelectric member 120 to be efficiently transferred to a target by matching sound impedances of the piezoelectric member 120 and the target. The sound matching layer 130 is configured to have an intermediate value between the sound impedance of the piezoelectric member 120 and the sound impedance of the target. The sound matching layer 130 may be formed of a glass or resin material.

In this embodiment, the sound matching layer 130 is illustrated as including a first sound matching layer 132 and a second sound matching layer 134, which are formed of different materials to allow the sound impedance to be changed stepwise from the piezoelectric member 120 to the target.

The sound matching layer 130 is provided with a mounting groove 135. In this embodiment, the mounting groove 135 is illustrated as being formed on the second sound matching layer 134. The mounting groove 135 is formed to have a bracket ("⌋") shape open towards the backing layer 110. According to this embodiment, the piezoelectric member 120 is mounted on the mounting groove 135. The mounting groove 135 includes a contact part 136 and an extension part 138.

The contact part 136 is formed parallel to the piezoelectric member 120 and contacts the piezoelectric member 120. The contact part 136 is disposed in front of the piezoelectric member 120 to contact one side of the piezoelectric member 120.

The extension part 138 extends from the contact part 136 to the first connector 140. In this embodiment, the extension part 138 extends from opposite ends of the contact part 136 to the first connector 140. The extension part 138 is disposed at lateral sides of the piezoelectric member 120 to be separated therefrom.

The mounting groove 135 including the contact part 136 and the extension part 138 has the bracket ("⌋") shape open towards the backing layer 110. With this configuration, the piezoelectric member 120 mounted on the mounting groove 135 has upper and opposite lateral sides, that is, three sides thereof, surrounded by the contact part 136 and the extension part 138.

The sound matching layer 130 is interconnected to the piezoelectric member 120, so that electric connection between the sound matching layer 130 and the piezoelectric member 120 can be obtained.

In one example, the sound matching layer 130 is provided with electrodes 133. The electrodes 133 may be provided to the second sound matching layer 134, specifically, to the mounting groove 135 so as to be provided to the entirety of the mounting groove 135 including the contact part 136 and the extension part 138.

The electrodes 133 formed on the sound matching layer 130 are electrically connected to the electrodes formed on one

side of the piezoelectric member **120**, so that the sound matching layer **130** is interconnected to the piezoelectric member **120** via the electrodes electrically connected to one another. The electrodes may be formed of a 20 highly electrically conductive material, such as gold, silver or copper, by deposition, sputtering, plating, spraying or the like.

In another example, the sound matching layer **130** is directly connected to the piezoelectric member **120**. That is, the sound matching layer **130** is formed of the conductive material, such as gold, silver or copper, and directly electrically connected to the piezoelectric member **120**.

The sound matching layer **130** is electrically connected to the electrodes formed on the one side of the piezoelectric member **120**, so that interconnection between the sound matching layer **130** and the piezoelectric member **120** is obtained.

In the sound matching layer **130** formed of the electrically conductive material, the entirety of the sound matching layer **130** including the first and second sound matching layers **132**, **134** may be formed of the electrically conductive material, or only the second sound matching layer **134** connected to the piezoelectric member **120** may be formed of the electrically conductive material. Since the sound matching layer **130** is electrically connected to the electrodes formed on the one side of the piezoelectric member **120** without a separate electrode, interconnection between the sound matching layer **130** and the piezoelectric member **120** can be obtained.

The first connector **140** is interconnected to the sound matching layer **130**. In this embodiment, the first connector **140** includes, but is not limited to, a flexible printed circuit board (FPCB). The first connector **140** may include a printed circuit board or any configuration capable of supplying signals or electricity as well as the printed circuit board (PCB).

The first connector **140** is formed with wiring electrodes (not shown). The wiring electrodes are formed on surfaces of the first connector **140** contacting the sound matching layer **130** and are electrically connected to the sound matching layer **130**.

The first connector **140** is respectively disposed on the opposite lateral sides of the sound matching layer **130** on which the extension part **138** is located. Each of the first connector **140** contacts the extension part **138** in a state of being inserted into a space between the extension part **138** and the backing layer **110**.

Each of the first connector **140** contacting the extension part **138** is interconnected to the extension part **138** via the wiring electrodes electrically connected to the extension part **138**.

In this embodiment, the first connector **140** is disposed so as not to overlap the piezoelectric member **120** and is interconnected only to the extension part **138**. Herein, the interconnection of the first connector **140** only to the extension part **138** means that the first connector **140** is interconnected only to the sound matching layer **130** through interconnection between the first connector **140** and the extension part **138**, and does not mean that the first connector **140** is not interconnected to other parts of the sound matching layer **130**, for example, the contact part **136** of the sound matching layer **130**.

The first connector **140** is interconnected to the sound matching layer **130** through the extension part **138**, and are interconnected only to one side of the piezoelectric member **120** through the contact part **136** of the sound matching layer **130** without interconnection to the other side of the piezoelectric member **120**.

The second connector **150** is interconnected to the piezoelectric member **120**. In this embodiment, the second connector

150 includes, but is not limited to, a flexible printed circuit board (FPCB). The second connector **150** may include a printed circuit board or any configuration capable of supplying signals or electricity as well as the printed circuit board (PCB).

The second connector **150** is formed with wiring electrodes (not shown). The wiring electrodes are formed on a surface of the second connector **150** contacting the other side of the piezoelectric member **120** and are electrically connected to the other side of the piezoelectric member **120**.

According to this embodiment, the second connector **150** is disposed in front of the backing layer **110** to contact the other side of the piezoelectric member **120**. The second connector **150** is interconnected to the other side of the piezoelectric member **120** via electrical connection between the wiring electrodes and the electrodes formed on the other side of the piezoelectric member **120**.

On the other hand, although not shown in the drawings, the probe for an ultrasonic diagnostic apparatus according to this embodiment may further include a lens layer (not shown) disposed in front of the sound matching layer **130** to focus forwardly traveling ultrasound waves on a predetermined point.

FIG. 4 is a flowchart of a method of manufacturing a probe for an ultrasonic diagnostic apparatus according to one embodiment of the invention.

Next, referring to FIGS. 1 to 4, a method of manufacturing a probe for an ultrasonic diagnostic apparatus according to one embodiment will be described.

To manufacture the probe according to this embodiment, a first connector **140** is stacked on a second connector **150**, in S10.

Here, each of the first connector **140** is stacked on a front side of the second connector **150**, that is, on a side of the second connector **150** having wiring electrodes of the second connector **150** formed thereon, to be separated from the second connector **150** such that the wiring electrodes of the second connector **150** are exposed between the first connector **140**. Preferably, the first connector **140** is separated from each other by a distance corresponding to the distance between an extension part **138** at one side of a mounting groove **135** and an extension part **138** at the other side of the mounting groove **135** provided to a sound matching layer **130**.

The first connector **140** and the second connector **150** are stacked on a backing layer **110**. Here, the first connector **140** and the second connector **150** may be stacked as a stacked assembly on the backing layer **110** or may be stacked thereon in such a way of stacking the second connector **150** on the backing layer **110**, followed by stacking the first connector **140** on the second connector **150**.

Then, a piezoelectric member **120** is stacked on the second connector **150** between the first connector **140**, in S20. That is, the piezoelectric member **120** is stacked in front of the second connector **150** to be disposed on the portion of the second connector **150** exposed between the first connector **140**.

As a result, the second connector **150** is interconnected to the piezoelectric member **120** by electrical connection of the second connector **150** to electrodes formed on one side of the piezoelectric member **120**, and the first connector **140** is disposed so as not to overlap the piezoelectric member **120**.

Additionally, the sound matching layer **130** is mounted on the piezoelectric member **120** and the first connector **140** such that the piezoelectric member **120** is inserted into the mounting groove **135**, in S30.

When the sound matching layer **130** is stacked on the piezoelectric member **120** and the first connector **140**, one

side of the piezoelectric member **120** contacts a contact part **136** of the mounting groove **135**, and the first connector **140** is disposed so as not to overlap the piezoelectric member **120** and contacts the extension part **138** of the mounting groove **135**.

As a result, the piezoelectric member **120** is electrically connected to the contact part **136** through the electrodes formed on the one side of the piezoelectric member **120** to interconnect with the sound matching layer **130**, and the first connector **140** is electrically connected to the extension part **138** through the wiring electrodes to interconnect with the sound matching layer **130**.

The piezoelectric member **120** may be interconnected to the first connector **140** by the interconnections between the piezoelectric member **120** and the sound matching layer **130** and between the first connector **140** and the sound matching layer **130**.

Then, the stacked piezoelectric member **120**, sound matching layer **130**, first connector **140** and second connector **150** are interconnected through a single bonding operation. That is, interconnection between one side of the piezoelectric member **120** and the sound matching layer **130**, interconnection between the other side of the piezoelectric member **120** and the second connector **150**, interconnection between the sound matching layer **130** and the first connector **140** is obtained through the single bonding operation, in **S40**. Here, the first connector **140** may be interconnected only to the sound matching layer **130**. The bonding operation may be carried out using conductive or non-conductive adhesives.

On the other hand, in this embodiment, the first connector **140** is stacked on the second connector **150**, and the piezoelectric member **120** is stacked on the second connector **150**, followed by stacking the sound matching layer **130** on the piezoelectric member **120** and the first connector **140**. However, it should be noted that the method of manufacturing a probe for an ultrasonic diagnostic apparatus is not limited to the sequence described above, and the processes of the method may be performed in a different sequence or at the same time.

In the method of manufacturing a probe for an ultrasonic diagnostic apparatus, the stacked piezoelectric member **120**, sound matching layer **130**, first connector **140** and second connector **150** are interconnected through a single bonding operation, instead of complicated and laborious operation of directly connecting the individual wiring electrodes of the first and second connectors **140**, **150** to the electrodes of the piezoelectric member **120** with the first and second electrodes **140**, **150** not stably positioned, so that the first and second connectors **140**, **150** may be interconnected to the piezoelectric member **120**.

The probe **100** for an ultrasonic diagnostic apparatus manufactured by the method according to the embodiment permits interconnection of the piezoelectric member **120** to the first and second connectors **140**, **150** to be performed rapidly and easily through a single bonding operation, thereby reducing manufacturing time while facilitating the manufacture of the probe.

Further, the probe according to the embodiment allows interconnection of the piezoelectric member **120** to the first and second connectors **140**, **150** to be performed, with the first and second connectors **140**, **150** stably positioned, so that durability and uniformity of connected portions are enhanced, thereby preventing deterioration in performance of the probe due to failure of the connection between the piezoelectric member **120** and the first and second connectors **140**, **150**.

Further, according to the embodiment, since the first connector **140** is connected to the piezoelectric member **120** via the sound matching layer **130** instead of being directly connected thereto, the first connector **140** is not disposed between the backing layer **110** and the piezoelectric layer **120**, so that performance of the piezoelectric member **120** can be enhanced and the length of the first connector **140** is decreased while reducing influence of impedance, thereby reducing manufacturing costs.

Although some embodiments have been provided to illustrate the invention in conjunction with the drawings, it will be apparent to those skilled in the art that the embodiments are given by way of illustration only, and that various modifications and equivalent embodiments can be made without departing from the spirit and scope of the invention. The scope of the invention should be limited only by the accompanying claims.

What is claimed is:

1. A probe for an ultrasonic diagnostic apparatus, comprising:
 - a sound matching layer having a mounting groove, a first electrode formed on the sound matching layer;
 - a piezoelectric member having an upper face and a lower face, the piezoelectric member mounted within the mounting groove such that the upper face is coupled to the sound matching layer, a second electrode formed on the piezoelectric member;
 - a first connector coupled to the sound matching layer; and
 - a second connector coupled to the first connector and to the lower face of the piezoelectric member,
 wherein the mounting groove comprises:
 - a contact part formed parallel to the piezoelectric member and coupled to the upper face of the piezoelectric member; and
 - an extension part extending from the contact part towards the first connector,
 wherein the first electrode is provided in a shape corresponding to the contact part and the extension part so as to contact the second electrode formed on one side of the piezoelectric member,
 - wherein the first electrode is provided to the entirety of the mounting groove including the contact part and the extension part,
 - wherein the first connector is coupled to the first electrode provided on the extension part, and
 - wherein the first connector is arranged between the extension part and the second connector.
2. The probe according to claim 1, wherein the first connector comprises a right first connector and a left first connector.
3. The probe according to claim 2, wherein the right first connector is coupled to the extension part and the second connector, and the right first connector and the second connector are adjacent one another.
4. The probe according to claim 2, wherein the left first connector is coupled to the extension part and the second connector, and the left first connector and the second connector are adjacent one another.
5. The probe according to claim 1, wherein the first connector comprises a flexible printed circuit board (FPCB).
6. The probe according to claim 1, wherein the second connector comprises a flexible printed circuit board (FPCB).
7. The probe according to claim 1, wherein the first connector is disposed on a portion of the first electrode that does not contact the piezoelectric member.

专利名称(译)	用于超声诊断设备的探针及其制造方法		
公开(公告)号	US9414809	公开(公告)日	2016-08-16
申请号	US12/912656	申请日	2010-10-26
[标]申请(专利权)人(译)	李成宰 朴贞LIM KIM JAE YK		
申请(专利权)人(译)	李成宰 朴贞LIM KIM JAE YK		
当前申请(专利权)人(译)	三星MEDISON CO. , LTD.		
[标]发明人	LEE SUNG JAE PARK JUNG LIM KIM JAE YK		
发明人	LEE, SUNG JAE PARK, JUNG LIM KIM, JAE YK		
IPC分类号	A61B8/00 B06B1/06 G10K11/00 H04R17/00 H04R31/00		
CPC分类号	A61B8/4281 B06B1/0622 G10K11/004 Y10T29/49005		
代理机构(译)	MCDERMOTT WILL & EMERY LLP		
优先权	1020090103771 2009-10-29 KR		
其他公开文献	US20110105906A1		
外部链接	Espacenet USPTO		

摘要(译)

公开了一种用于超声诊断设备的探针及其制造方法。探针包括具有安装槽的声音匹配层，安装在安装槽上的压电元件，互连到声音匹配层的第一连接器，以及互连到压电元件的第二连接器。探针允许压电构件与第一和第二连接器的互连通过单次键合操作快速且容易地执行，从而减少制造时间，同时便于制造探针。

